

MATERIAL DECLARATION SHEET



Material Number	CDNBS04 Series			
Product Line	Diode Products			
Compliance Date	1 Jan 2006			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Lead Frame	Lead Frame	0.0457	Copper	7440-50-8	95.2	48.99	51.46
				Tin	7440-31-5	4.8	2.475	
2	Die	Silicon	0.01434	Silicon	7440-21-3	97.95	15.82	16.15
				Other material		1.99	0.3229	
3	Gold Bond Wire	Conductor	0.000352	Gold	7440-57-5	98.99	0.3924	.3964
				Silicon	7440-21-3	0.98	0.0039	
4	Silver Paste	Die Attach	0.000808	Tin	7440-31-5	96	0.7097	0.9099
				Silver	7440-22-4	3.5	0.150	
				Copper	7440-50-8	0.5	0.050	
5	Molding Component	Outer	0.0276	Silica fused	60676-86-0	85	26.42	31.08
				Epoxy resin	68928-70-1	10	3.108	
				Phenol resin	29690-82-2	6	1.865	
		Total weight	0.0888					

This Document was updated on: 18-march 2009

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.